

**IN THE SPECIFICATION**

**Please amend the paragraph beginning on page 1, line 4 as follows:**

This application is related to commonly assigned U.S. patent application, ~~Micon no. 02-1122~~, serial no. [[\_\_\_\_]] 10/414,147, filed on 15 April 2003, now U.S. Patent No. 6,740,392, entitled "Improved Surface Barriers for Copper and Silver Interconnections Produced by a Damascene Process," which is hereby incorporated by reference in its entirety.

**Please amend the paragraph beginning on page 6, line 4 as follows:**

In addition to copper, gold and silver also offer lower resistivities than aluminum. These materials also have a significantly lower adhesion to oxides than aluminum. These materials as well as aluminum have relatively poor adhesion to polymers. Processes that offer significant improvements to the barrier adhesion art for the bottom and the sidewall damascene or dual damascene structures are provided by the present inventor in U.S. patent 6,376,370 issued 23 April 2002, U.S. patent 6,420,262 issued 30 July 2002, U.S. patent 6,426,289 issued 16 July 2002, and U.S. patent application, ~~Micon no. 02-1122~~, serial no. [[\_\_\_\_]] 10/414,147, filed on 15 April 2003, now U.S. Patent No. 6,740,392, which are hereby incorporated by reference.